

Listing of Claims in the Application

This Listing of Claims replaces, without prejudice, all previous versions and listing of claims in this Application.

1. (Currently amended) A master plate for fabricating a stamper plate for production of an optical storage medium with information such as a CD or a DVD, the master plate comprising a substrate and a photoresist layer provided thereon, while parts of the photoresist layer exposed to light of a predetermined frequency are soluble in a solvent, characterized in that the solubility exhibits a ~~trend~~ gradient along the normal to the photoresist layer, the solubility on the side near the substrate being less soluble than the solubility on the opposite, upper side of the photoresist layer.
2. (Original) A master plate according to claim 1, characterized in that said photoresist layer comprises a first subphotoresist layer provided, with or without an intervening adhesive layer, on the substrate, and a second subphotoresist layer which is provided on the first subphotoresist layer, the solubility in said solvent of exposed parts of the first subphotoresist layer being less than the solubility in the solvent of exposed parts of the second subphotoresist layer.
3. (Previously presented) A master plate according to claim 1, characterized in that parts of the photoresist layer exposed to laser light of a frequency in the frequency band of 200-500 nm are soluble in the solvent.
4. (Previously presented) A master plate according to claim 3, characterized in that the solvent is an alkaline solvent.
5. (Currently amended) A method for fabricating a master plate for fabricating a stamper plate, wherein on a substrate a photoresist layer is provided, wherein parts of the photoresist layer exposed to light of a predetermined frequency are soluble in a solvent, characterized in that the photoresist layer is provided by providing a first material and a

second material on the substrate, such that the solubility of exhibits a gradient along the normal to the photoresist photoresist layer, the solubility on the side near the substrate is being less than the solubility on the opposite, upper side of the photoresist layer.

6. (Original) A method according to claim 5, characterized in that the method further comprises the following steps:

providing a first subphotoresist layer of the first material on a substrate wherein exposed parts of the first subphotoresist layer have a first solubility in a solvent;

providing a second subphotoresist layer of a second material on the first subphotoresist layer, wherein exposed parts of the second subphotoresist layer have a second solubility in the solvent, and wherein the second solubility is greater than the first solubility.

7. (Original) A method according to claim 6, characterized in that the method further comprises the following steps:

providing directly on the substrate an adhesive such as n-(2-amino-ethyl)-3-aminopropyl-trimethoxysilane, hexamethyldisilazane (HMDS) and/or trimethylsilyldiethylamine (TMSDEA);

providing a photoresist layer on the adhesive applied;

allowing formation, through a crosslinking reaction between the adhesive and the photoresist layer provided directly thereon, of the first subphotoresist layer and, situated thereon, the second subphotoresist layer.

8. (Original) A method according to claim 7, characterized in that the adhesive, directly upon application, is rinsed with a rinsing agent such as water for a relatively short period of time.

9. (Original) A method according to claim 8, characterized in that the relatively short rinsing period with water takes 5 seconds at a maximum.

10. (Currently amended) A method according to claim 6, characterized in that the

first subphotoresist layer, after being applied, is given a treatment as a result of which the solubility in the solvent of ~~exposed~~ treated parts of the first subphotoresist layer decreases definitively.

11. (Original) A method according to claim 10, characterized in that the treatment consists in irradiating the first subphotoresist layer with UV light and/or in a heat treatment.

12. (Previously presented) A method according to claim 6, characterized in that the subphotoresist layers are exposed according to a predetermined pattern, after which the thus exposed parts are dissolved in the solvent and are rinsed off, and after which the surface of the photoresist layer of the master plate is provided with a relatively thin metal layer.

13. (Previously presented) A method according to claim 5, characterized in that the method further comprises the step of fabricating a stamper plate by a galvanic process as a negative copy of the master plate.

14. (Original) A method according to claim 13, characterized in that the method further comprises the step of fabricating an optical storage medium by an injection molding process with the stamper plate.